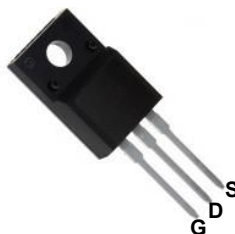
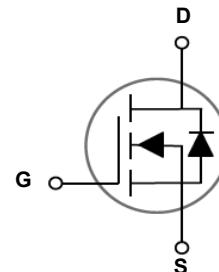


Main Product Characteristics

| | |
|---------------|------------|
| $V_{(BR)DSS}$ | 1000V |
| $R_{DS(ON)}$ | 3.6Ω (typ) |
| I_D | 4A |



TO-220F



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFU10004 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Max. | Unit | |
|---|-----------------|---------------------------|------|---|
| Drain-Source Voltage | V_{DSS} | 1000 | V | |
| Gate-Source Voltage | V_{GSS} | ±30 | V | |
| Continuous Drain Current | I_D | $T_C = 25^\circ\text{C}$ | 4 | A |
| | | $T_C = 100^\circ\text{C}$ | 2.7 | A |
| Pulsed Drain Current ¹ | I_{DM} | 16 | A | |
| Single Pulsed Avalanche Energy ² | E_{AS} | 88 | mJ | |
| Power Dissipation | P_D | 36 | W | |
| Thermal Resistance, Junction to Case | $R_{\theta JC}$ | 3.47 | °C/W | |
| Thermal Resistance, Junction to Ambient | $R_{\theta JA}$ | 62.5 | °C/W | |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | °C | |

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Condition | Min. | Typ. | Max. | Unit |
|---|---------------|--|------|------|-----------|----------|
| Off Characteristic | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=250\mu A$ | 1000 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 1000V, V_{GS} = 0V,$ $T_J = 25^\circ\text{C}$ | - | - | 1 | |
| | | $V_{DS} = 800V, V_{GS} = 0V,$ $T_J = 125^\circ\text{C}$ | - | - | 50 | μA |
| Gate to Body Leakage Current | I_{GSS} | $V_{DS} = 0V, V_{GS} = \pm 30V$ | - | - | ± 100 | nA |
| On Characteristics | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 2 | - | 4 | V |
| Static Drain-Source on-Resistance ³ | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 2.0A$ | - | 3.6 | 4.3 | Ω |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 25V, V_{GS} = 0V,$ $f = 1.0\text{MHz}$ | - | 689 | - | pF |
| Output Capacitance | C_{oss} | | - | 68 | - | pF |
| Reverse Transfer Capacitance | C_{rss} | | - | 13 | - | pF |
| Total Gate Charge | Q_g | $V_{DD} = 800V, I_D = 4A,$ $V_{GS} = 10V$ | - | 19 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 4 | - | nC |
| Gate-Drain("Miller") Charge | Q_{gd} | | - | 11 | - | nC |
| Switching Characteristics | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD} = 500V, I_D = 4A,$ $R_G = 25\Omega$ | - | 37 | - | ns |
| Turn-on Rise Time | t_r | | - | 16 | - | ns |
| Turn-off Delay Time | $t_{d(off)}$ | | - | 143 | - | ns |
| Turn-off Fall Time | t_f | | - | 37 | - | ns |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Maximum Continuous Drain to Source Diode Forward Current | I_S | | - | - | 4 | A |
| Maximum Pulsed Drain to Source Diode Forward Current | I_{SM} | | - | - | 16 | A |
| Drain to Source Diode Forward Voltage | V_{SD} | $V_{GS} = 0V, I_{SD} = 4A$ | - | - | 1.4 | V |
| Reverse Recovery Time | t_{rr} | $V_{GS} = 0V, I_S = 4A,$ $di/dt = 100A/\mu s$ | - | 980 | - | ns |
| Reverse Recovery Charge | Q_{rr} | | - | 1.4 | - | μC |

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. $V_{DD} = 50V, L = 10\text{mH}, R_G = 25\Omega, \text{Starting } T_J = 25^\circ\text{C}$

3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 1\%$

Typical Electrical and Thermal Characteristic Curves

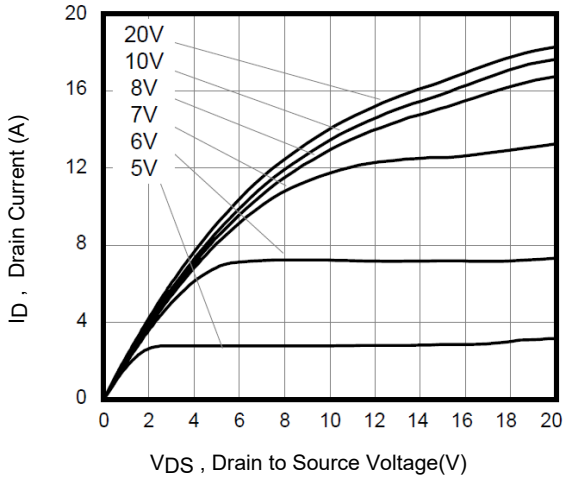


Figure 1. Output Characteristics

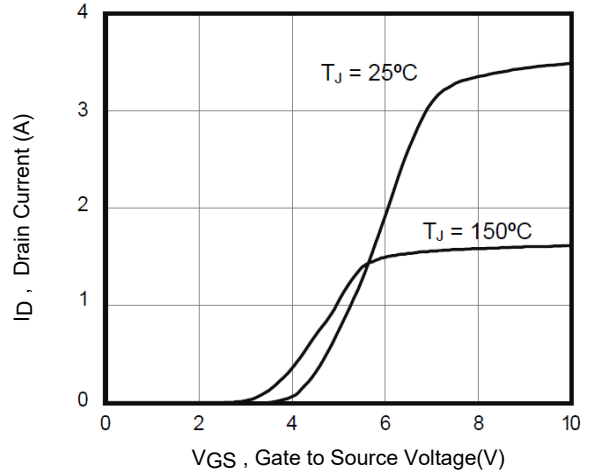


Figure 2. Transfer Characteristics

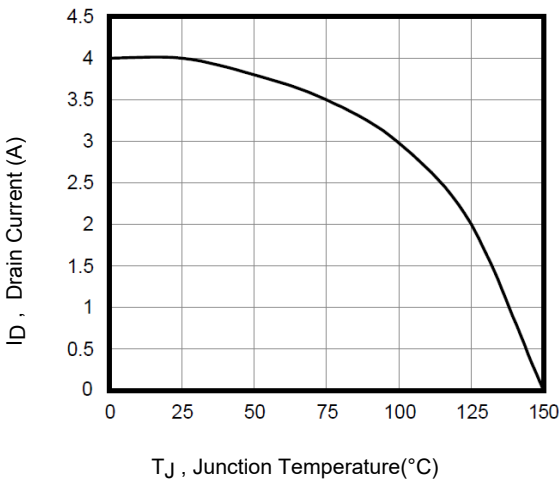


Figure 3. Current De-rating

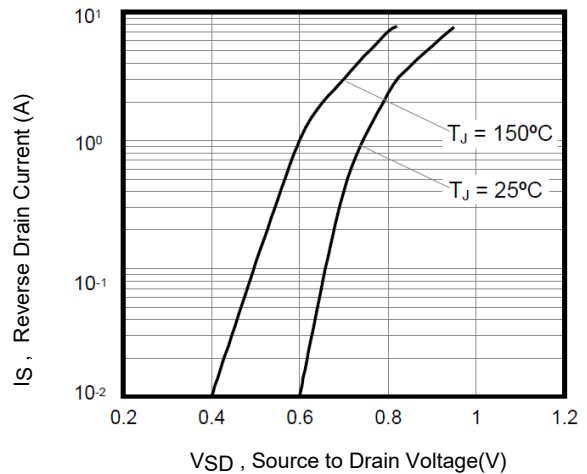


Figure 4. Body Diode Characteristics

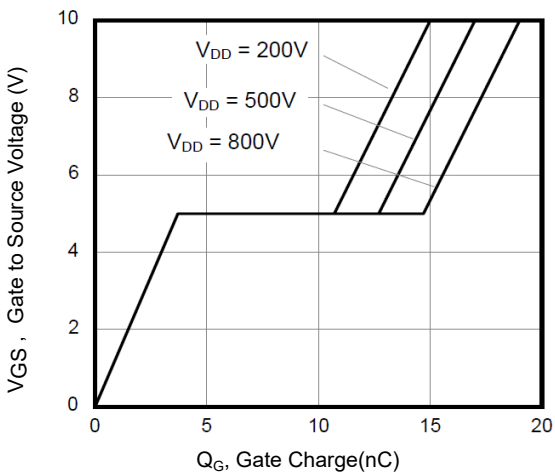


Figure 5. Gate Charge

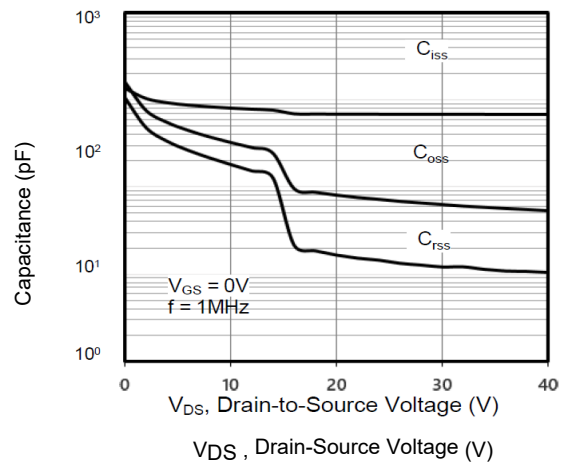


Figure 6. Capacitance Characteristics

Typical Electrical and Thermal Characteristic Curves

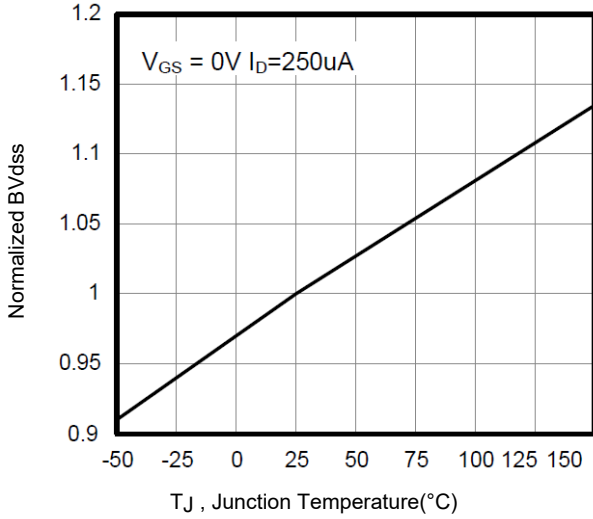


Figure 7. Normalized BVdss vs. Junction Temperature

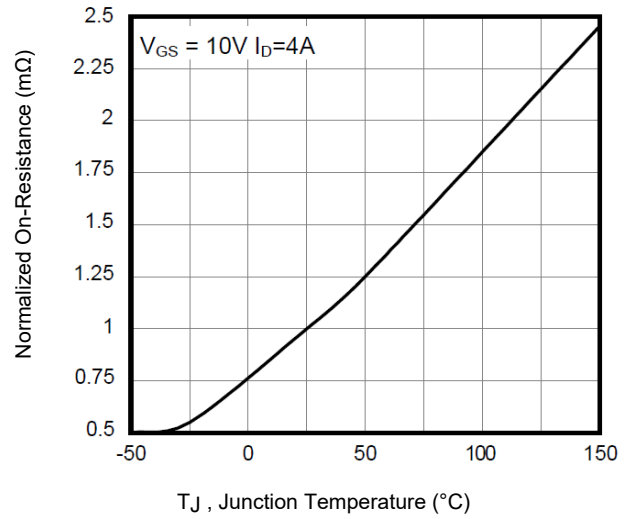


Figure 8. Normalized RDSon vs. Junction Temperature

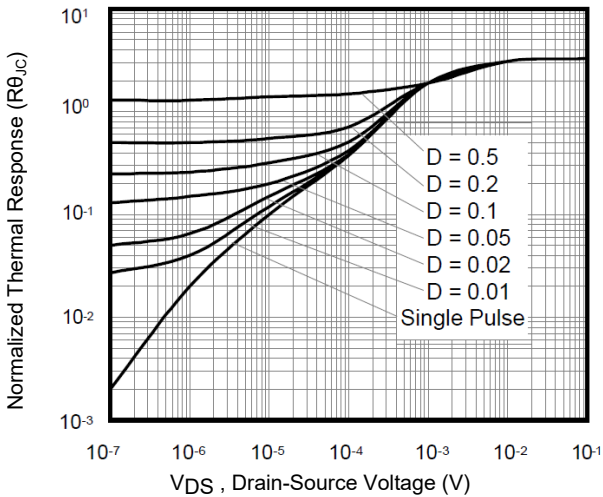


Figure 9. Transient Thermal Impedance

Test Circuit & Waveform

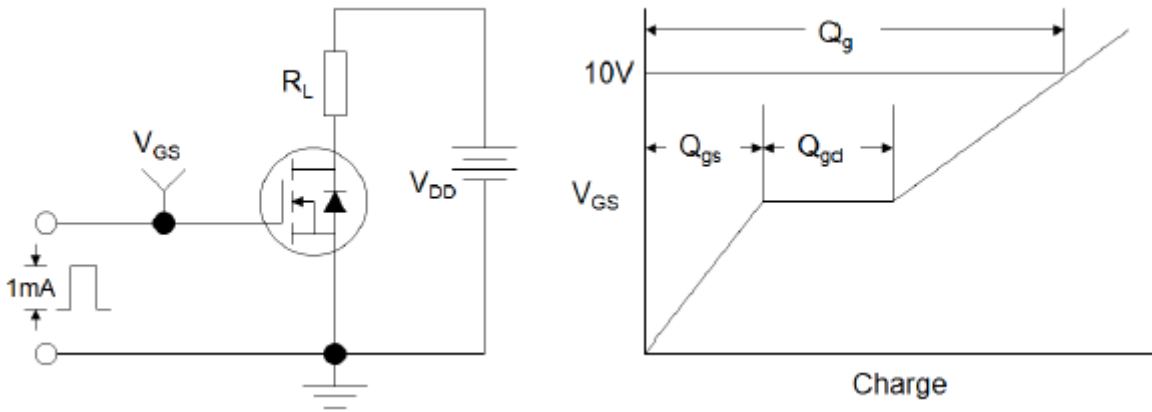


Figure 10. Gate Charge Test Circuit & Waveform

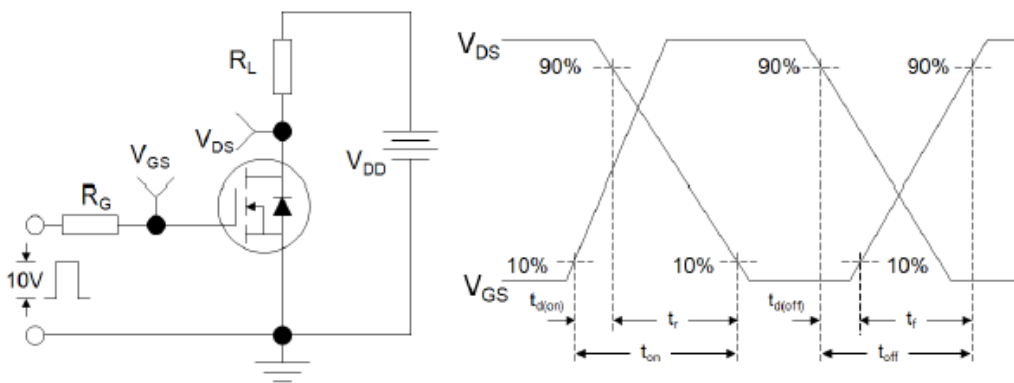


Figure 11. Resistive Switching Test Circuit & Waveforms

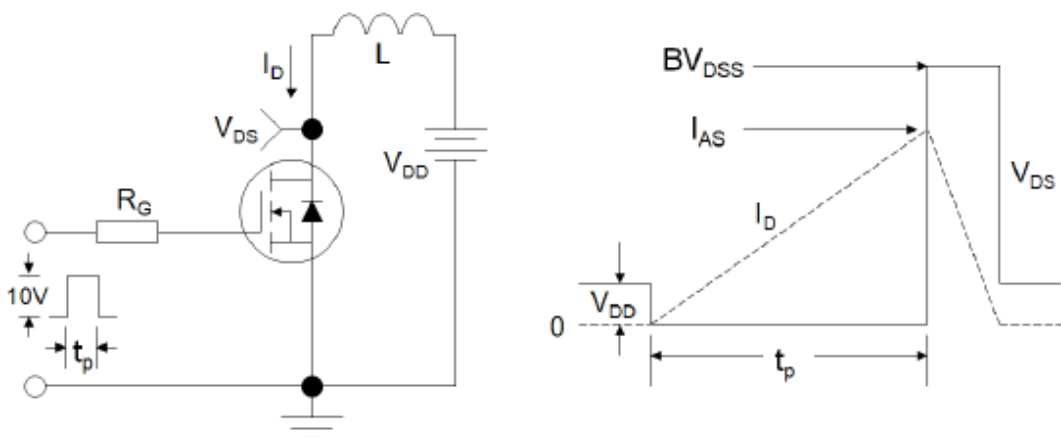
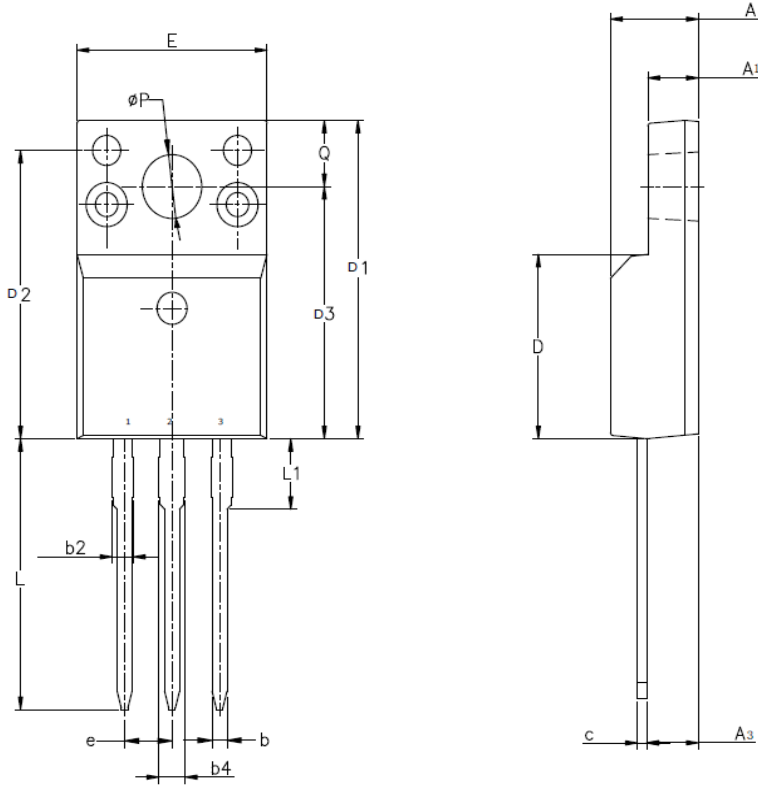


Figure 12. Unclamped Inductive Switching Test Circuit & Waveforms

Package Outline Dimensions

TO-220F



| Ref. | Dimensions | | | | | | |
|------|-------------|------|------|----|-------|------|-------|
| | Millimeters | | | | | | |
| | Min. | Typ. | Max. | | Min. | Typ. | Max. |
| A | 4.50 | | 4.90 | D | 8.80 | | 9.39 |
| A1 | 2.45 | | 2.83 | D1 | 15.8 | | 16.2 |
| A3 | 2.56 | | 3.00 | D2 | 14.1 | | 14.6 |
| b | 0.74 | 0.80 | 0.9 | D3 | 12.3 | | 12.9 |
| b2 | 0.96 | | 1.19 | E | 9.80 | | 10.40 |
| b4 | 1.14 | | 1.70 | L | 13.20 | | 13.70 |
| c | 0.46 | | 0.65 | L1 | 3.37 | | 3.67 |
| Q | 3.20 | | 3.40 | ΦP | 3.10 | | 3.60 |
| e | 2.54 BSC | | | | | | |